



## Material Content Data Sheet



<b>Sales Product Name</b>		IPL65R210CFD		<b>Issued</b>		23. January 2018		
<b>MA#</b>		MA001141032						
<b>Package</b>		PG-VSON-4-1		<b>Weight*</b>		191.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.459	4.95	4.95	49483	49483
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		67	
	non noble metal	zinc	7440-66-6	0.051	0.03		266	
	non noble metal	iron	7439-89-6	1.017	0.53		5321	
wire	non noble metal	copper	7440-50-8	41.300	21.61	22.18	216060	221714
	non noble metal	copper	7440-50-8	1.104	0.58	0.58	5775	5775
	encapsulation	organic material	carbon black	1333-86-4	0.208	0.11		1089
	plastics	epoxy resin	-	10.724	5.61		56104	
	inorganic material	silicondioxide	60676-86-0	93.187	48.75	54.47	487505	544698
leadfinish	non noble metal	tin	7440-31-5	2.397	1.25	1.25	12542	12542
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1318	1318
solder	noble metal	silver	7440-22-4	0.160	0.08		835	
	non noble metal	tin	7440-31-5	0.128	0.07		668	
	non noble metal	lead	7439-92-1	6.095	3.19	3.34	31885	33388
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		39	
	non noble metal	zinc	7440-66-6	0.030	0.02		157	
	non noble metal	iron	7439-89-6	0.601	0.31		3146	
	non noble metal	copper	7440-50-8	24.418	12.77	13.10	127740	131082
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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